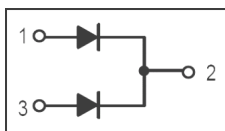


/ Descriptions

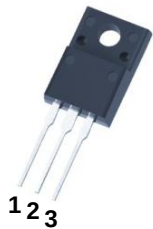
/ Features

/ Applications

/ Equivalent Circuit



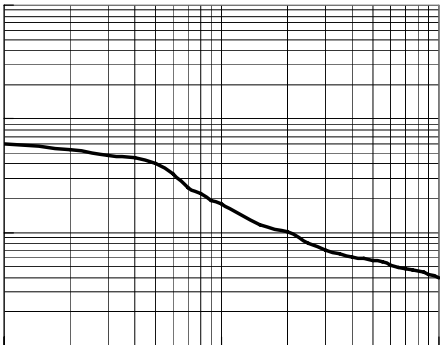
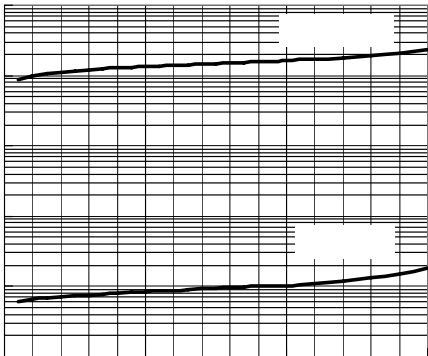
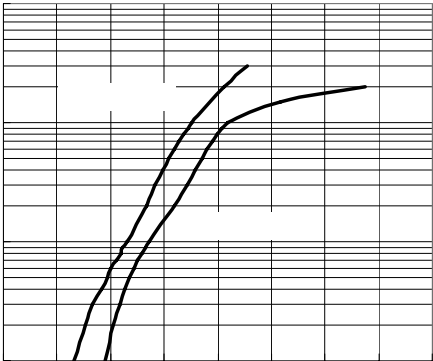
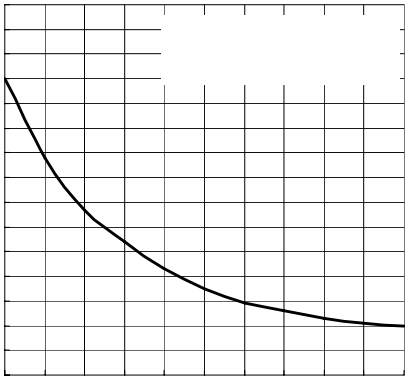
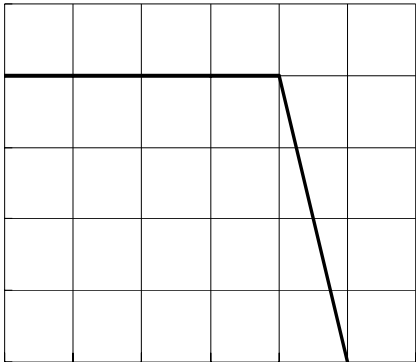
/ Pinning



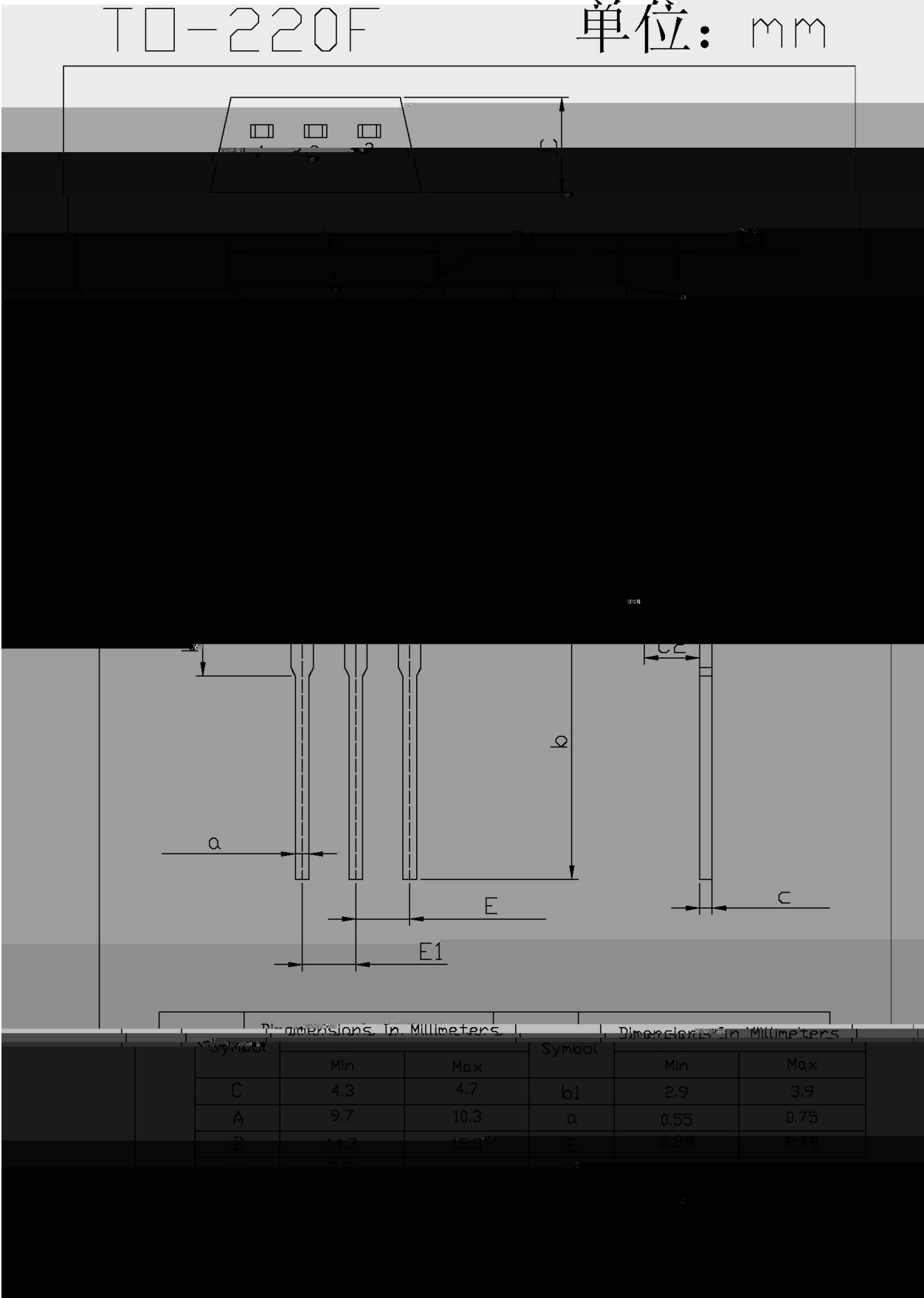
/ h_{FE} Classifications & Marking

	θ		

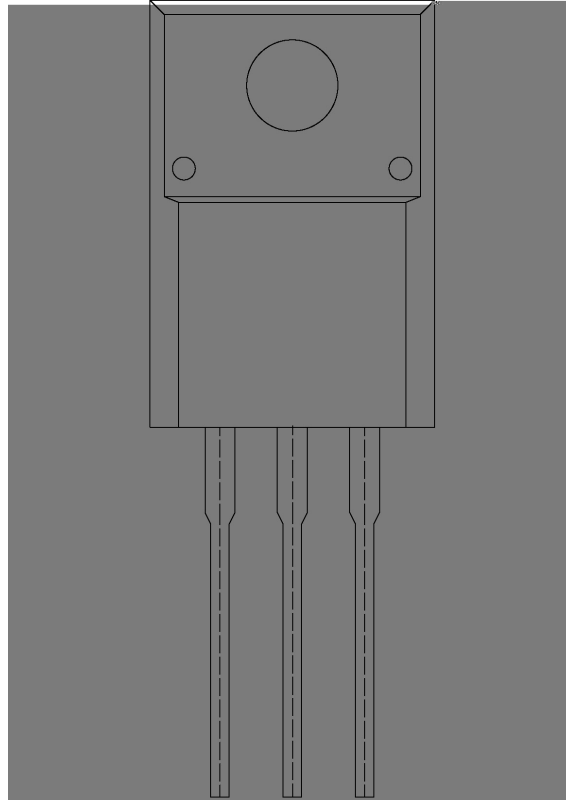
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

封装形式	包装数量					包装尺寸		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices